

MOSFET N-channel enhancement switching transistor**BSS83****DESCRIPTION**

Symmetrical insulated-gate silicon MOS field-effect transistor of the N-channel enhancement mode type. The transistor is sealed in a SOT143 envelope and features a low ON resistance and low capacitances. The transistor is protected against excessive input voltages by integrated back-to-back diodes between gate and substrate.

Marking code:

BSS83 = M74

APPLICATIONS

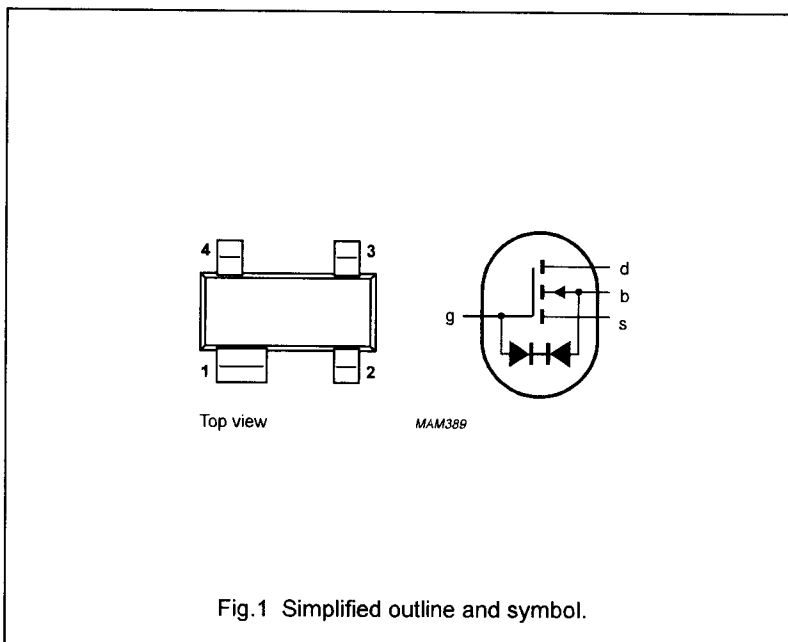
- analog and/or digital switch
- switch driver

PINNING

- 1 = substrate (b)
 2 = source
 3 = drain
 4 = gate

Note

1. Drain and source are interchangeable.

**QUICK REFERENCE DATA**

Drain-source voltage	V_{DS}	max.	10 V
Source-drain voltage	V_{SD}	max.	10 V
Drain-substrate voltage	V_{DB}	max.	15 V
Source-substrate voltage	V_{SB}	max.	15 V
Drain current (DC)	I_D	max.	50 mA
Total power dissipation up to $T_{amb} = 25\text{ }^{\circ}\text{C}$	P_{tot}	max.	230 mW
Gate-source threshold voltage $V_{DS} = V_{GS}; V_{SB} = 0;$ $I_D = 1\text{ }\mu\text{A}$	$V_{GS(th)}$	> <	0.1 V 2.0 V
Drain-source ON-resistance $V_{GS} = 10\text{ V}; V_{SB} = 0; I_D = 0.1\text{ mA}$	$R_{DS(on)}$	<	45 Ω
Feed-back capacitance $V_{GS} = V_{BS} = -15\text{ V};$ $V_{DS} = 10\text{ V}; f = 1\text{ MHz}$	C_{rss}	typ.	0.6 pF

MOSFET N-channel enhancement switching transistor

BSS83

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Drain-source voltage	V_{DS}	max.	10 V
Source-drain voltage	V_{SD}	max.	10 V
Drain-substrate voltage	V_{DB}	max.	15 V
Source-substrate voltage	V_{SB}	max.	15 V
Drain current (DC)	I_D	max.	50 mA
Total power dissipation up to $T_{amb} = 25\text{ }^{\circ}\text{C}^{(1)}$	P_{tot}	max.	230 mW
Storage temperature range	T_{stg}		$-65\text{ to }+150\text{ }^{\circ}\text{C}$
Junction temperature	T_j	max.	125 $^{\circ}\text{C}$

THERMAL RESISTANCE

From junction to ambient in free air ⁽¹⁾	$R_{th\ j-a}$	=	430 K/W
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MOSFET N-channel enhancement switching transistor

BSS83

CHARACTERISTICS

 $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

Drain-source breakdown voltage

$V_{GS} = V_{BS} = -5\text{ V}; I_D = 10\text{ nA}$

$V_{(BR)DSX}$	>	10 V
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Source-drain breakdown voltage

$V_{GD} = V_{BD} = -5\text{ V}; I_D = 10\text{ nA}$

$V_{(BR)SDX}$	>	10 V
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Drain-substrate breakdown voltage

$V_{GB} = 0; I_D = 10\text{ nA}; \text{open source}$

$V_{(BR)DBO}$	>	15 V
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Source-substrate breakdown voltage

$V_{GB} = 0; I_D = 10\text{ nA}; \text{open drain}$

$V_{(BR)SBO}$	>	15 V
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Drain-source leakage current

$V_{GS} = V_{BS} = -2\text{ V}; V_{DS} = 6,6\text{ V}$

I_{DSoff}	<	10 nA
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Source-drain leakage current

$V_{GD} = V_{BD} = -2\text{ V}; V_{SD} = 6,6\text{ V}$

I_{SDoff}	<	10 nA
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Forward transconductance at $f = 1\text{ kHz}$

$V_{DS} = 10\text{ V}; V_{SB} = 0; I_D = 20\text{ mA}$

g_{fs}	>	10 mS
	typ.	15 mS

Gate-source threshold voltage

$V_{DS} = V_{GS}; V_{SB} = 0; I_D = 1\text{ }\mu\text{A}$

$V_{GS(th)}$	>	0,1 V
	<	2,0 V

Drain-source ON-resistance

$I_D = 0,1\text{ mA};$

$V_{GS} = 5\text{ V}; V_{SB} = 0$

R_{DSon}	<	70 Ω
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$V_{GS} = 10\text{ V}; V_{SB} = 0$

R_{DSon}	<	45 Ω
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$V_{GS} = 3,2\text{ V}; V_{SB} = 6,8\text{ V (see Fig.4)}$

R_{DSon}	typ.	80 Ω
	<	120 Ω

Gate-substrate zener voltages

$V_{DB} = V_{SB} = 0; -I_G = 10\text{ }\mu\text{A}$

$V_{Z(1)}$	>	12,5 V
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$V_{DB} = V_{SB} = 0; +I_G = 10\text{ }\mu\text{A}$

$V_{Z(2)}$	>	12,5 V
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Capacitances at $f = 1\text{ MHz}$

$V_{GS} = V_{BS} = -15\text{ V}; V_{DS} = 10\text{ V}$

Feed-back capacitance

C_{rss}	typ.	0,6 pF
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Input capacitance

C_{iss}	typ.	1,5 pF
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Output capacitance

C_{oss}	typ.	1,0 pF
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Switching times (see Fig.2)

$V_{DD} = 10\text{ V}; V_i = 5\text{ V}$

t_{on}	typ.	1,0 ns
t_{off}	typ.	5,0 ns

Note

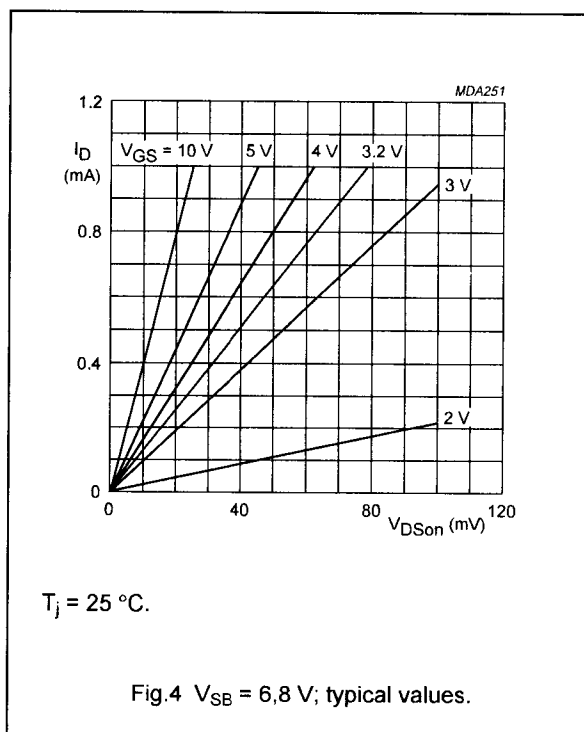
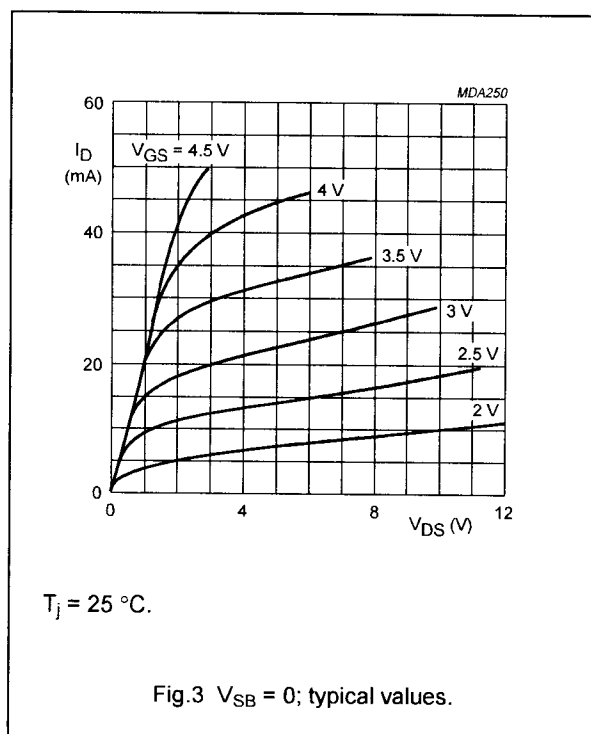
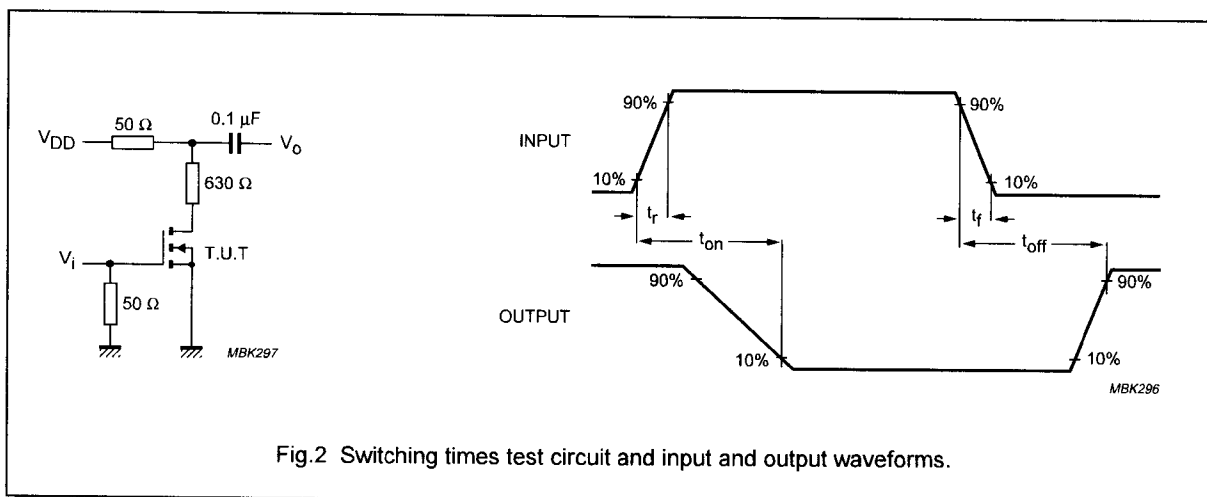
1. Device mounted on a ceramic substrate of $8\text{ mm} \times 10\text{ mm} \times 0,7\text{ mm}$.

MOSFET N-channel enhancement switching transistor

BSS83

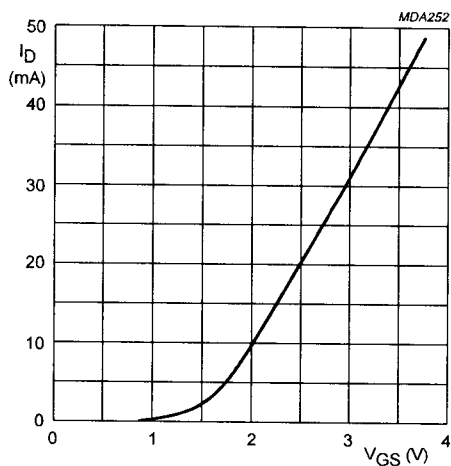
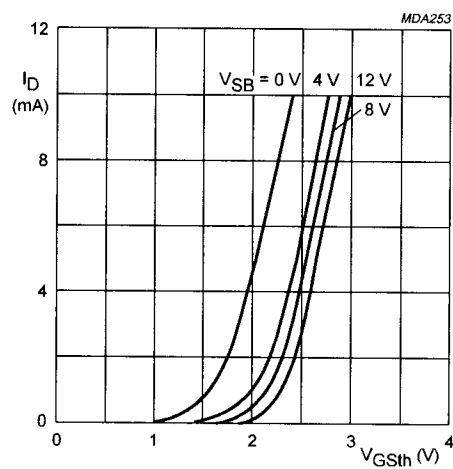
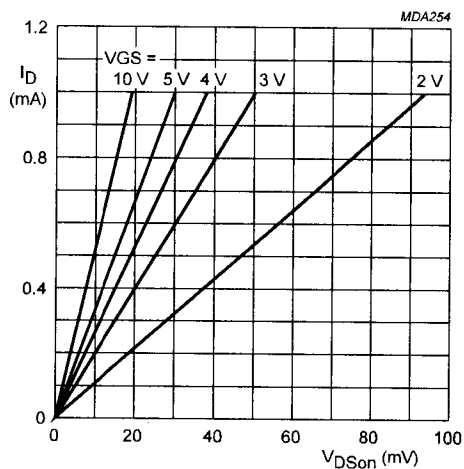
Pulse generator:

$R_i = 50 \Omega$
 $t_r < 0,5 \text{ ns}$
 $t_f < 1,0 \text{ ns}$
 $t_p = 20 \text{ ns}$
 $\delta < 0,01$



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BSS83

 $T_j = 25^\circ\text{C}$.Fig.5 $V_{DS} = 10\text{ V}$; $V_{BS} = 0$; typical values. $T_j = 25^\circ\text{C}$.Fig.6 $V_{DS} = V_{GS} = V_{GS(th)}$. $T_j = 25^\circ\text{C}$.Fig.7 $V_{SB} = 0$; typical values.

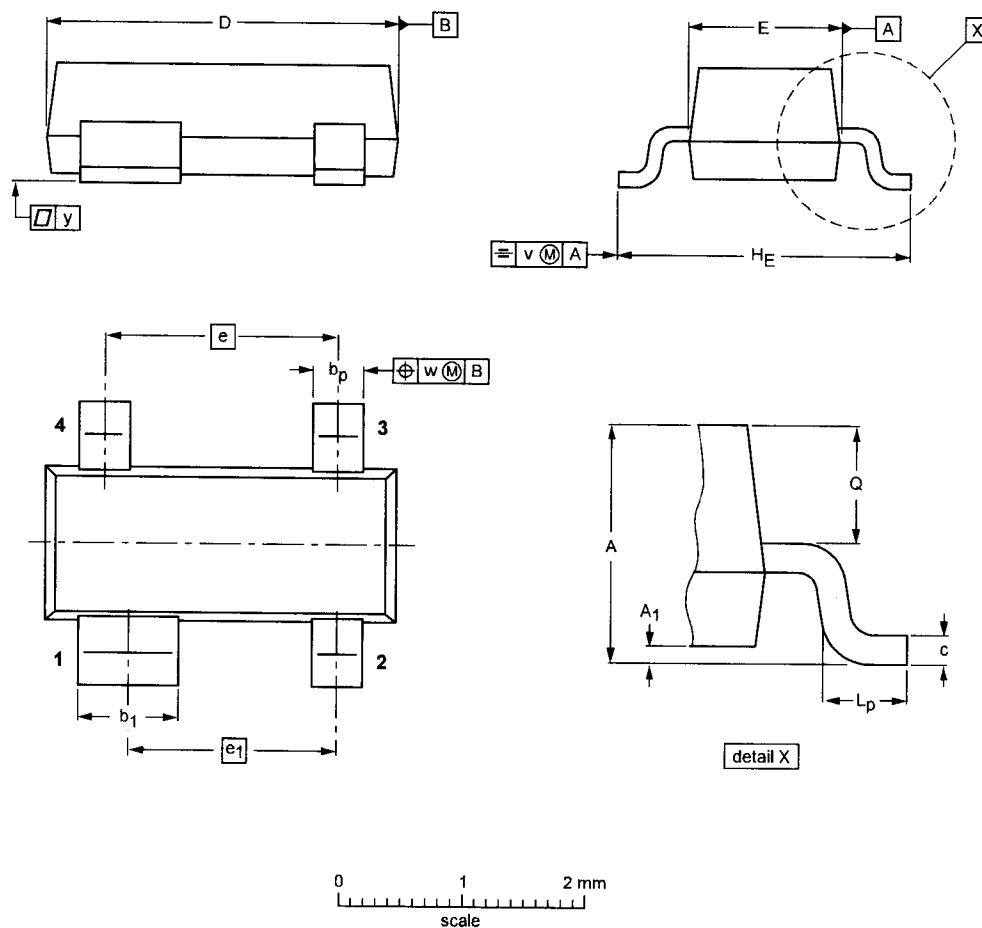
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BSS83

PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

SOT143B



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	b ₁	c	D	E	e	e ₁	H _E	L _p	Q	v	w	y
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT143B						97-02-28